

Amendments to the Specification:

After the title and before the first paragraph, please insert the following paragraph:

THIS APPLICATION IS A U.S. NATIONAL PHASE APPLICATION OF PCT INTERNATIONAL APPLICATION PCT/JP2004/018693.

Please replace the paragraph, beginning at page 3, line 27, with the following rewritten paragraph:

Further, as shown in Fig. 10D, mask films ~~2a~~22a and 22b are peeled from the both sides of prepreg sheet 21. Next, as shown in Fig. 10E, metal foils 25a and 25b such as copper are piled at the both sides of prepreg sheet 21. By heating and pressing with a heat press in this state, as shown in Fig. 10F, prepreg sheet 21 is compressed in thickness (t_2 = approximately 100 μm) and prepreg sheet 21 and metal foils 25a-25b are bonded to each other. As discussed above, metal foils 25a and 25b at both sides are electrically coupled with each other by using conductive paste 24 filled in through-holes 23 formed at a certain position. Furthermore, metal foils 25a and 25b at both sides are etched selectively, so that circuit patterns (not shown) are formed and the double-sided circuit board can be obtained.

Please replace the paragraph, beginning at page 17, line 4, with the following rewritten paragraph:

According to the method for manufacturing a circuit board of the second embodiment, in the same way as the first embodiment, solid conductive paste 4, which has been formed at the squeegee edge, is removed, and a paste-residue occurs at squeegee cleaning part 6. However, after that, because the squeegee edge is cleaned, conductive paste 4 is not remained on through-holes 3 within the product. Therefore, conductive paste 4 is filled stably. In addition, squeegee cleaning part 6 is formed by no-penetrated groove processing of mask film ~~2b~~22a, so that conductive paste 4 is filled into a depth of the groove in mask film 2b.